

## CALL FOR PAPERS

**ECTC Components & RF Program Committee**  
**CPMT RF & Wireless Technical Committee**

**58th ECTC May 27<sup>th</sup> – May 30<sup>th</sup>, 2008**

**Orlando, Florida USA**

The CPMT RF & Wireless Technical Committee and the ECTC Electronic Components & RF Program Committee encourage you to submit an abstract in the area of passive components & networks, RF and Microwave components and modules and subsystems.

**Discrete Passive Components:** Design, materials, processes and manufacturing considerations for discrete passive components-resistors, capacitors, inductors and passive networks.

**Integrated and Embedded Passive Components:** Design, materials, processing, modeling, manufacturing, and characterization of integrated/embedded passives on silicon, organic, ceramic and glass type substrates for digital, mixed signal, & RF applications

**Materials, Processing, Reliability, and Manufacturing of Electronic Components:** Design, Materials, Processing, yield and reliability aspects of electronic components

**New Technology Development for Electronic Components:** Technologies for on chip integration of passive components – silicon through vias, wafer level RDL, nano materials and processes; Technologies for substrate level integration – embedded passive and active components, component integration on ultra thin substrates

**RF and Microwave Components:** Integrated antennas, filters, baluns, RFID/sensors, RF MEMS, tunable devices and switches, high power and high efficiency RF/Microwave power amplifiers- design, technology and high frequency characterization

**RF and Microwave Modules:** Module Integration technologies in semiconductor, organic and glass substrates – System in Package, System on Chip, Package on Package, 3D integration

**SUBMISSIONS:** Please submit abstracts using the ECTC web site: [www.ectc.net](http://www.ectc.net) by October 15, 2007. Abstracts must comply with the guidelines outlined at the website. To have your paper considered for inclusion in the “Components & RF” focused sessions **YOU MUST SELECT**

**“ElectronicComponents & RF” committee as your PRIMARY subcommittee preference** when you submit your abstract.

Craig Gaw, Chair - CPMT RF & Wireless TC, Freescale Semiconductor Inc., [c.a.gaw@ieee.org](mailto:c.a.gaw@ieee.org)

Mahadevan K. Iyer, Chair - ECTC RF & Components TC, Georgia Institute of Technology, [mahadevan.iyer@ece.gatech.edu](mailto:mahadevan.iyer@ece.gatech.edu)

## CALL FOR PAPERS

**ECTC Emerging Technologies Program Committee**

**58th ECTC May 27<sup>th</sup> – May 30<sup>th</sup>, 2008**

**Orlando, Florida USA**

The ECTC Emerging Technologies Program Committee encourages you to submit an abstract to ECTC 2007 in the areas of biomedical, organic, and nanotechnology packaging.

**Bio and Biomedical Electronics:** - Bio sensors & bio packaging - Microfluidic packaging - Implantable or embedded sensors - Bio compatible materials - Electronic packaging used in medical devices - Biomedical electronics manufacturing - Biomedical electronics design and reliability - Wireless communication for patient monitoring - Remote healthcare management - Reliability of Biomedical Devices - Interface of microelectronics to the neural systems

**Organic/Flexible Electronics:** - Materials: Active Materials, Encapsulation Materials, Patterning Materials, Thermal/Electrical Rheological Properties, Analysis, Inspection and Measurement Methods - Deposition Methods: Ink-jet, Vacuum, Gravure/Printing, Flexographic Deposition, and Process Integration - Applications: OLED, RFID, wearable, biomedical, passive and active components, design issues

**Nano-Electronics:** - Nano-Electronics Packaging - Devices, Assembly, Interconnects - Nano-Electronics Materials - Nano-Electronics Applications - Sensors, Actuators, and Detectors - Nano-Electronics Integration - Nano-Electronics Fabrication and Modules - Nano-Electronics Reliability and Failure Analysis - Nano-Electronics Metrology Tools - Nano-Electronics Design and Modeling

**SUBMISSIONS:** Please submit abstracts using the ECTC web site: [www.ectc.net](http://www.ectc.net) by October 15, 2007. Abstracts must comply with the guidelines outlined at the website. To have your paper considered for inclusion in the “Emerging Technologies” focused sessions **YOU MUST SELECT**

**“Emerging Technologies” committee as your PRIMARY subcommittee preference** when you submit your abstract.

Michael Toepper, Chair – ECTC Emerging Technology PC, IZM, [toepper@izm.fhg.com](mailto:toepper@izm.fhg.com)

Debendra Mallik, Assistant Chair – ECTC Emerging Technology PC, Intel Corporation, [dmallik@ieee.org](mailto:dmallik@ieee.org)

## CALL FOR PAPERS

### ECTC **OPTOELECTRONICS** Program Committee

**58th ECTC May 27<sup>th</sup> – May 30<sup>th</sup>, 2008**  
**Orlando, Florida USA**

Papers are solicited on all topics pertaining to the design, development, and technology of packaging optoelectronics and photonic components, devices, circuitry and systems.

**Topics of interest include:**

- **High Power Optoelectronics and Fiber Laser Packaging:** High-power laser diodes, bars / stacks, and Fiber lasers – including beam combining, coupling, wave-length control, hermetic packaging and thermal issues.
- **High-Brightness LED Packaging for Lighting and Commercial Applications:** Package and optical design, assembly methods, thermal management, reliability, color temperature control, phosphor materials, and volume manufacturing.
- **Optical Component Thermal Management and Reliability:** Optical component thermal management, package design, device performance, failure modes and reliability
- **Micro-optical Packaging and Manufacturing Technology:** Low cost designs, novel optics, assembly methodology and automation technology
- **Silicon Photonics Devices and Packaging:** Optical devices in Silicon, hybrid integration, FR performance, Silicon optical waveguides, photonics circuits and packaging
- **Optical Interconnects:** Integrated optics, high-speed and parallel transceivers, board-level waveguides, optical backplanes, fiber optic connectors and hybrid integration
- **Advanced Materials for Optoelectronics:** Substrates, devices, components and assembly materials

**SUBMISSIONS:** Please submit abstracts using the ECTC web site by **October 15, 2007**. Abstracts must comply with the guidelines outlined at the website. To have your paper considered for inclusion in the “Optoelectronics” focused sessions **YOU MUST SELECT “Optoelectronics” committee as your PRIMARY subcommittee preference** when you submit your abstract.

Please visit:

[www.ectc.net](http://www.ectc.net)

You may also submit directly to the committee chair below – please include mailing address, telephone number, FAX number and e-mail:

Allen Earman  
Novalux LDX  
Tel: 408-730-3833  
Fax: 408-730-3967  
[aearman@novalux.com](mailto:aearman@novalux.com)

## 16th Conference on

### **Electrical Performance of Electronic Packaging**

**EPEP 2007**

Sponsors:

**IEEE Microwave Theory and Techniques Society**  
**IEEE Components, Packaging and Manufacturing Technology Society**

**October 29-31, 2007**

**Renaissance Atlanta Hotel**  
**Atlanta, Georgia**



The general subject of the meeting is the electrical modeling, design, analysis, and characterization of electronic interconnections and packaging structures. This meeting is the premier conference dealing with advanced and emerging issues in electrical design of interconnect structures and assurance of Signal Integrity. EPEP '07 has an outstanding technical program featuring more than 70 technical papers. The conference will feature paper sessions, a poster session and keynote speakers.

For further information, please see the web site at

[www.epep.org](http://www.epep.org)